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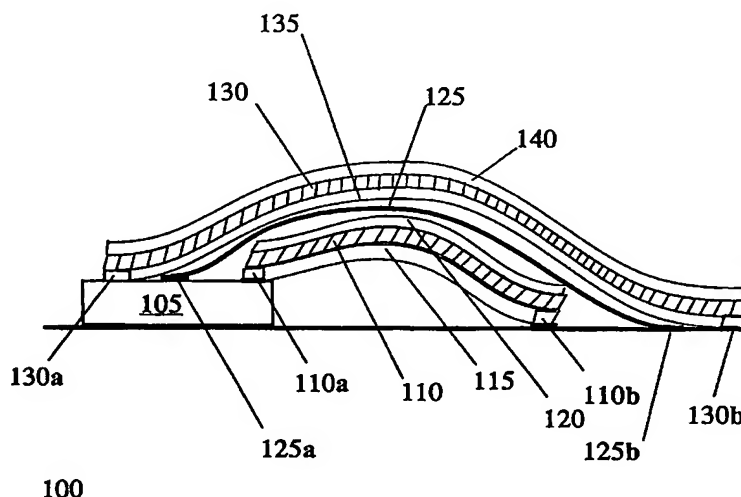
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(54) Title: HIGH DENSITY PACKAGE INTERCONNECT WIRE BOND STRIP LINE AND METHOD THEREFOR



(57) Abstract: In an example embodiment, an integrated circuit (105) is placed in a package (100), the package having signal pad connections, power connections, and ground connections. A lower strip line (110) is bonded by coupling a first ground connection (110a) of the IC (105) to a first package substrate ground connection (110b). After bonding the lower strip line, a plurality of wires (125) is bonded by a plurality of signal pads (125a) on a device die (105) being coupled to signal pad connections (125b) on the package substrate (100), the plurality of signal pads (125a) being in proximity to the first ground connection (110a) and the plurality of wires (125) maintained at a first predetermined distance from the lower strip line (110). After bonding the plurality of wires (125), an upper strip line (130) is bonded by coupling a second ground connection (130a) of the IC (105) with a second package substrate ground connection (130b), the upper strip line maintained at a second predetermined distance from the plurality of wires (125).

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